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Attorney Docket No. 5649-905

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Hong-Sik Jeong et al.

Confirmation No.: 5150

Serial No.: 10/008,700

Group Art Unit: 2825

Filed: December 7, 2001

Examiner: Chuong A. Luu

For: METHODS OF MANUFACTURING INTEGRATED CIRCUIT DEVICES
HAVING AN ENCAPSULATED INSULATION LAYER

Date: February 24, 2004

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

AMENDMENT

Sir:

Applicants provide the present Amendment to address the issues raised in the Official Action mailed October 24, 2003. Applicant provides the present Amendment pursuant to the rules stated in revised 37 C.F.R. 1.121 that became effective on July 30, 2003.

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